



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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3/7/03
J. Skel

In re the Application of:

Taylor R. Efland

Docket No.: TI-31678

Serial No.: 09/975,630

Examiner: Andujar, L.

Filed: 10/12/01

Art Unit: 2826

For: Circuit Structure Integrating the Power Distribution Functions of Circuits
and Leadframes into the Chip Surface

Amendment under 37 CFR 1.111

Assistant Commissioner of Patents
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that this correspondence is being deposited with
the U.S. Postal Service as First Class Mail in an envelope addressed
to: Assistant Commissioner for Patents, Washington, D.C. 20231 on

2-24-03

Michael K. Skrehot, Reg. No. 36,682

Dear Sir:

The following amendments and remarks are offered in response to the Examiner's Office Action dated 10/24/02. They are respectfully submitted as a full and complete response to that Action. A petition for a one-month extension of time accompanies this paper. The Commissioner is hereby requested and authorized to charge any fees necessary for the filing of the enclosed papers to deposit account number 20-0668 of Texas Instruments Incorporated.

Please amend the application as follows:

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